

Atty Ref/Docket No.: 884.419US1



101728029

To the Honorable Commissioner of Patents and Trademarks, please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Tee Onn Chong, Seng Hooi Ong and Robert L. Sankman

*MRB*  
*5-15-01*

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2625 Walsh Avenue

City: Santa Clara State: CA ZIP: 95051

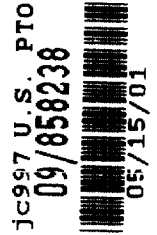
Additional name(s) & address(es) attached? [ ]Yes [X]No

Additional name(s) of conveying party(ies) attached? [ ]Yes [X]No

3. Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other \_\_\_\_\_

Execution Date: May 11, 2001, May 10, 2001, April 26, 2001



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: May 11, 2001, May 10, 2001, April 26, 2001

A. Patent Application No.(s)

*09858238*

B. Patent No.(s)

Additional numbers attached? [ ]Yes [X]No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Ann M. McCrackin

Address: Schwegman, Lundberg, Woessner & Kluth, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Please charge any additional fees or credit any overpayments to our  
Deposit account number: 19-0743

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ann M. McCrackin/Reg. No. 42,858  
Name of Person Signing

*Ann M. McCrackin*  
Signature

May 15, 2001  
Date

Total number of pages including cover sheet: 5

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## ASSIGNMENT

WHEREAS, WE, Tee Onn Chong, residing at BLK A3-3 (INAD), #1-4, Mutiara Perdana, Jalan Lengkok Kelicap off Jalan Relau, Sg. Ara, Penang 11900, Malaysia, and Seng Hooi Ong, residing at 41 Lorong Tiong Mas 5, 14100 Simpang Ampat, Seberang Perai, Penang 14100, Malaysia, and Robert L. Sankman, residing at 4753 E. Pearce Road, Phoenix, AZ 85044, made certain new and useful inventions and improvements for which We executed an application for Letters Patent of the United States on Even Date Herewith, which is entitled ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS.

AND WHEREAS, Intel Corporation, a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 2625 Walsh Avenue, Santa Clara, CA 95051, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefore;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.



## ASSIGNMENT

WHEREAS, WE, Tee Onn Chong, residing at BLK A3-3 (INAI), #1-4, Mutiara Perdana, Jalan Lengkok Kelicap off Jalan Relau, Sg. Ara, Penang 11900, Malaysia, and Seng Hooi Ong, residing at 41 Lorong Tiong Mas 5, 14100 Simpang Ampat, Seberang Perai, Penang 14100, Malaysia, and Robert L. Sankman, residing at 4753 E. Pearce Road, Phoenix, AZ 85044, made certain new and useful inventions and improvements for which We executed an application for Letters Patent of the United States on Even Date Herewith, which is entitled ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS.

AND WHEREAS, Intel Corporation, a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 2625 Walsh Avenue, Santa Clara, CA 95051, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefore;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, we do hereby agree that we and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me/us and that full right to convey the same as herein expressed is possessed by us.

IN TESTIMONY WHEREOF, I have hereunto set my hand this \_\_\_\_ day of \_\_\_\_\_, 2001.

\_\_\_\_\_  
Tee Onn Chong

IN TESTIMONY WHEREOF, I have hereunto set my hand this \_\_\_\_ day of \_\_\_\_\_, 2001.

\_\_\_\_\_  
Seng Hooi Ong

IN TESTIMONY WHEREOF, I have hereunto set my hand this 26 day of April, 2001.

  
\_\_\_\_\_  
Robert L. Sankman